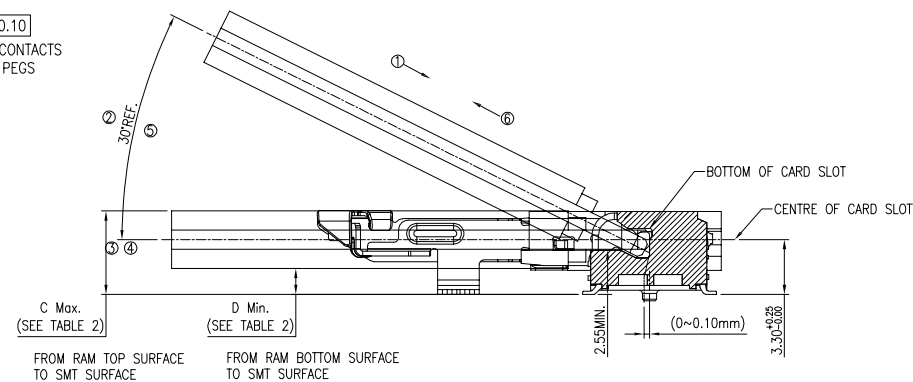
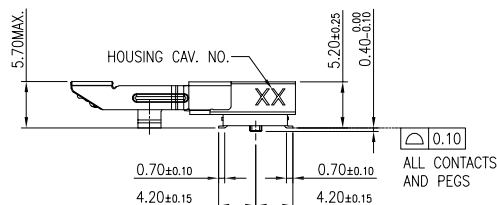
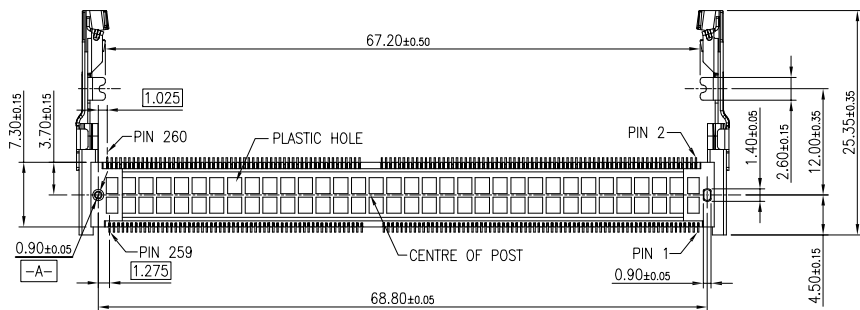
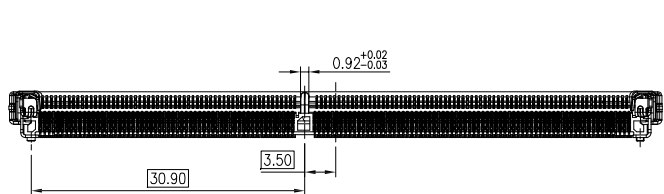
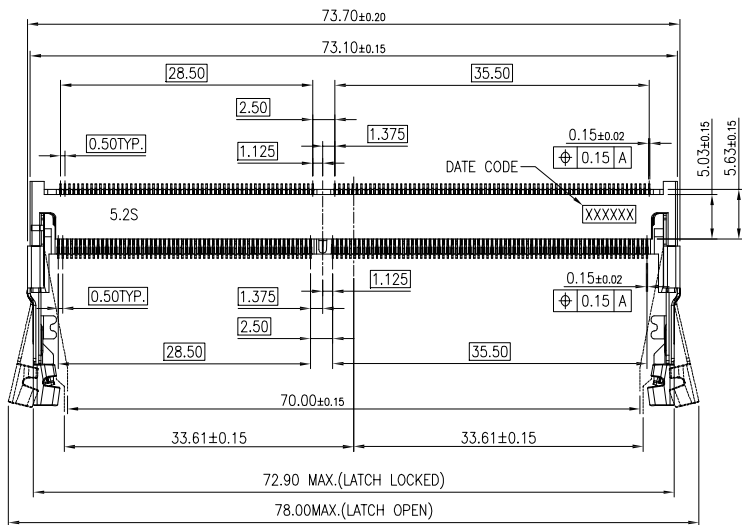




# NOTES

## 1.MATERIAL

- 1-1 HOUSING:LCP THERMOPLASTIC.UL94V-0. COLOR:BLACK.
- 1-2 CONTACT:HIGH-PERFORMANCE COPPER ALLOY.
- 1-3 LATCH:STAINLESS STEEL.
- 1-4 PEG:STAINLESS STEEL.

## 2.FINISH

- 2-1 CONTACT:GOLD PLATING 1~3u" ON CONTACT AREA  
AND 1~3u"GOLD PLATING ON SOLDER AREA  
NICKEL 50u"~150u" UNDER-PLATING ALL OVER
- 2-2 PEG:50~150u" TIN PLATING OVER  
50~150u" NICKEL UNDER-PLATING ALL OVER

## 3.MSL LEVEL: MSL(MOISTURE SENSITIVITY LEVEL)=1.

## 4.IR REFLOW:

THE PEAK TEMPRATURE ON THE BOARD SHALL BE  
MAINTAINED FOR 10 SECONDS AT 260±5°C.

## TOLERANCE

LINEAR ANGLES

X±0.40 X°± 3°

.X±0.30 .X\*±

.XX±0.20 .XX\*±

.XXX±0.10 .XXX\*±

**UMax** 东莞市友贸实业有限公司  
**conn** DONGGUAN UMAX ENTERPRISE LIMITED

APPD: Jason

MAT'L:

CHKD: Schumi

FINISH:

DRWN:Lei Songping

Q'TY:

TITLE: DDR4 SODIMM  
5.2H 260PIN STANDARD G/F  
TYPE.

PART NO. D4260-5201SR

DWG NO. C-D4260-52

| UNITS | SCALE | SHEET  | REV |
|-------|-------|--------|-----|
| MM    | 1 : 1 | 1 OF 2 | A0  |

| REV | ECN NO. | NAME | DATE |
|-----|---------|------|------|
|-----|---------|------|------|

CUSTOMER

